

## KLA Xactix E2 XeF2 Etcher

1. The Xactix E2 etcher is primarily used to etch Si isotropically with XeF<sub>2</sub>, which is suitable for MEMS processes. It can also isotropically etch Ge, C, W, and Mo.
2. XeF<sub>2</sub> etching is a dry, vapor-phase etching process that selectively removes silicon at room temperature. An RF power supply is not used and a plasma is not present.
3. The selectivity for Si/photoresist, Si/SiO<sub>2</sub> and Si/SiN is larger than 1000:1.
4. The Xactix E2 etcher can process samples from small coupons to 6" wafers.

